EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	((wafer dice) with (redistribution trace ((conductive wiring pattern$3 metal) near1 layer)) with (substrate carrier) with ((edge side) near2 (contact connector))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:28
L2	14	((wafer dice) same (redistribution trace ((conductive wiring pattern$3 metal) near1 layer)) same (substrate carrier) same ((edge side) near2 (contact connector))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:32
L3	10	2 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:29
L4	16	((wafer dice) and redistribut$3 and (substrate carrier) and ((edge side) near2 (contact connector))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:59
L5	4204	257/723,724.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:39
L6	1939	438/107,110.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:59
L7	5964	5 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 08:59
L8	27	7 and (wafer dice) and redistribut$3 and (substrate carrier) and ((edge side) near2 (contact connector)) and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 09:02